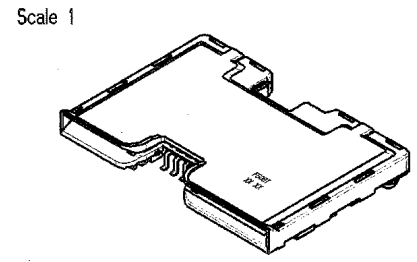
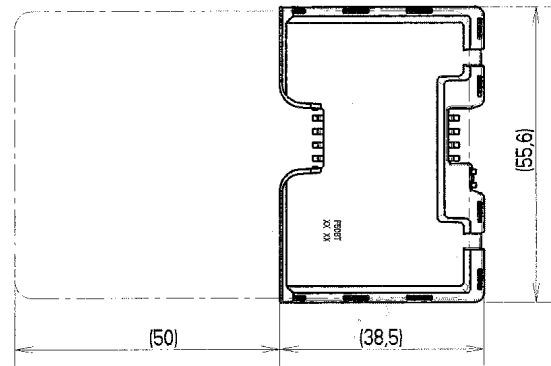
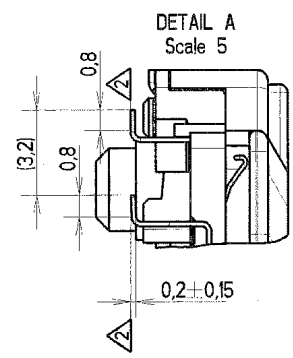
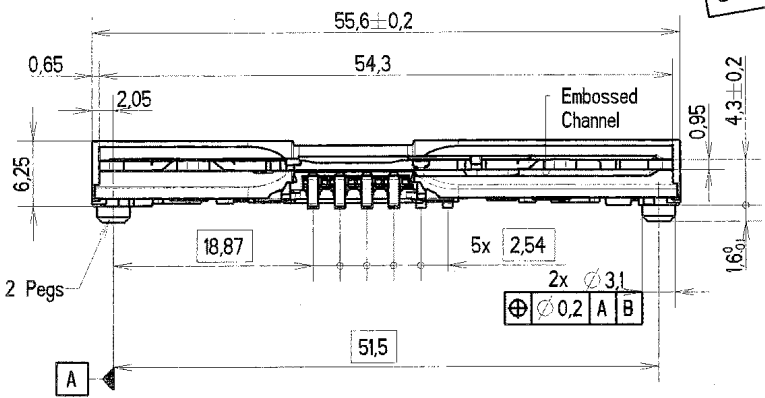
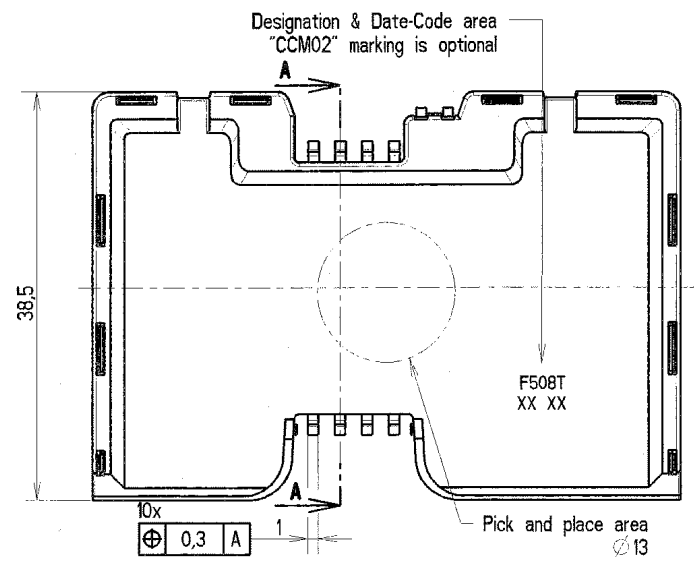
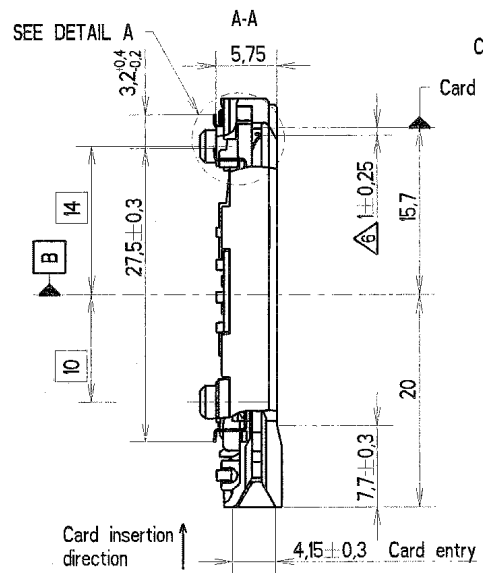
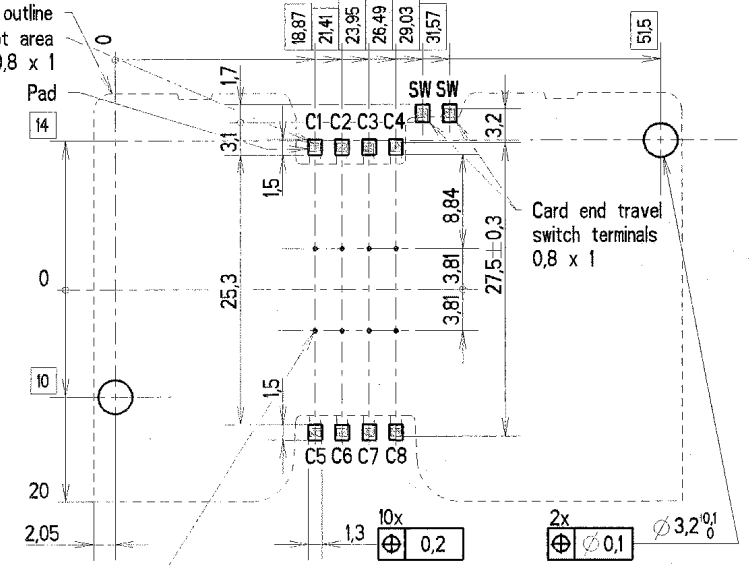


SYSTEM CONFIDENTIAL

REV.	N°	DCR	NATURE DE LA MODIFICATION	DATE	VISA
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RECOMMENDED PC BOARD LAYOUT (Component side)



Contact location according to ISO/IEC 7816-2

- Notes :
- 1 - Termination to PCB : SMT reflow soldering Temperature/time profile according to : C&K P5-LF-001 specification. Since there are no boardlocks, the connector must be held in place on the PCB across the top face of the cover.
 - 2 - Level of each contact tail compared to the nearest plastic stand-off. Coplanarity of metal soldering surfaces : 0,15 mm.
 - 3 - Recommendation for solder paste thickness > 0,2 mm.
 - 4 - 2,5 microns min tin plating on contact terminal areas and 0,1 microns min gold plating on switch terminal areas.
 - 5 - Contacts forces :
 - max 0,5 N per contact with max. card thickness.
 - min 0,2 N per contact with min. card thickness.

- 6 - Card end travel switch NO activates when the sliding card is 1 mm from the card stop.
- 7 - For packaging on tray, see document : cu 030278Y0041.
- 8 - In case of customer accessories integration requesting an interface with CCM, please ask C&K for a 3D model.

MATIERE	TOL LINEAIRE	TOL ANGULAIRE	TRAITEMENT	PROTECTION
SAUF INDIQUE :	± 0,1	± 2	ETAT DE SURFACE	DIMENSIONS CRITIQUEES
-COTES DONNEES AVANT PROTECTION			Ra	DIMENSIONS SPC
-BAUVRES ET ARETES VIVES SUPPRIMEES				LANGAGE
DESIGNE D.FERRATON	DATE 11-02-2009	ANALYSE Y	TAB. FAM. Y	PROVE Y
VERIFIE G.PINON	DATE 11-02-2009	REPLACE		
APPROUVE L.KUBAT	DATE 11-02-2009	DESIGNATION		
 C&K Components	PROJECTION 1-ER DIEDRE	CCM02-F508LFT		
	ECHELLE 2	SLIDING VERSION		
TAILLE A3	FEUILLE 1 / 1	NUMERO CU	2 pegs	
BP 359 - 39105 Dole - FRANCE -		1122M1YF508		

LE PLAN EST LA PROPRIETE DE C&K. COMPOSANTS SAS ET NE PEUT ETRE REPRODUIT OU COMMUNIQUE SANS SON AUTOPRISACON.